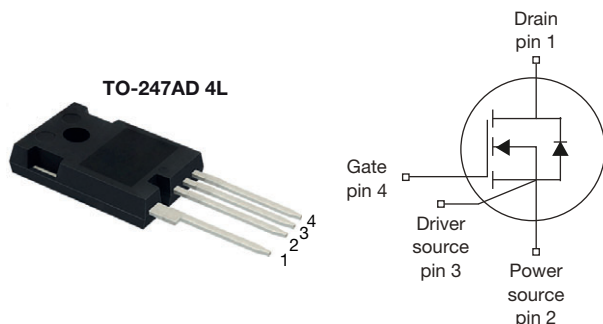


SF Series Power MOSFET With Fast Body Diode



RoHS
COMPLIANT
HALOGEN
FREE

FEATURES

- Latest generation SF series technology
- Low figure of merit (FOM) $R_{DS(on)} \times Q_g$
- Low effective capacitance ($C_{o(er)}$)
- Reduced switching and conduction losses
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Solar (PV inverters)

PRODUCT SUMMARY

V_{DS} (V) at T_J max.	700	
$R_{DS(on)}$ typ. (Ω) at 25 °C	$V_{GS} = 10$ V	0.080
Q_g max. (nC)	137	
Q_{gs} (nC)	29	
Q_{gd} (nC)	38	
Configuration	Single	

ORDERING INFORMATION

Package	TO-247AD 4L
Lead (Pb)-free and halogen-free	SiHL080N65SF-GE3

ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C, unless otherwise noted)

PARAMETER				SYMBOL	LIMIT	UNIT
Drain-source voltage				V_{DS}	650	V
Gate-source voltage				V_{GS}	± 20	
Continuous drain current ($T_J = 150\text{ }^{\circ}\text{C}$)	V_{GS} at 10 V	$T_C = 25\text{ }^{\circ}\text{C}$	I_D	46	A	
		$T_C = 100\text{ }^{\circ}\text{C}$		29		
Pulsed drain current ^a			I_{DM}	114		
Linear derating factor					3.2	W/ $^{\circ}\text{C}$
Single pulse avalanche energy ^b				E_{AS}	396	mJ
Maximum power dissipation				P_D	403	W
Operating junction and storage temperature range				T_J, T_{stg}	-55 to +150	$^{\circ}\text{C}$
Drain-source voltage slope			$T_J = 125\text{ }^{\circ}\text{C}$	dv/dt	100	V/ns
Reverse diode dv/dt ^d					100	

Notes

- Repetitive rating; pulse width limited by maximum junction temperature
- $V_{DD} = 120$ V, starting $T_J = 25$ °C, $L = 28.2$ mH, $R_g = 25$ Ω , $I_{AS} = 5.3$ A
- 1.6 mm from case
- $I_{SD} \leq I_D$, di/dt = 400 A/ μ s, starting $T_J = 25$ °C

**THERMAL RESISTANCE RATINGS**

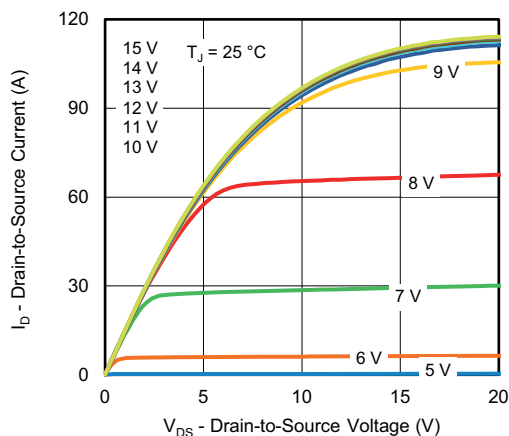
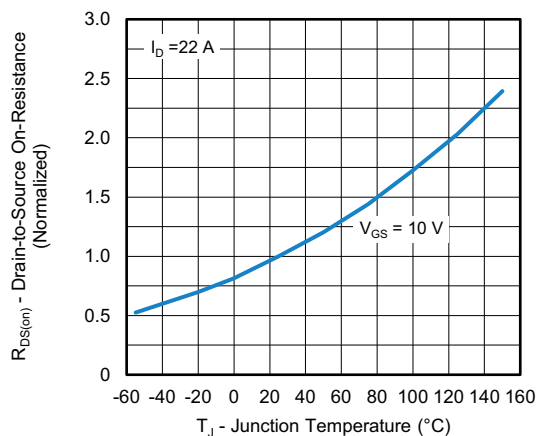
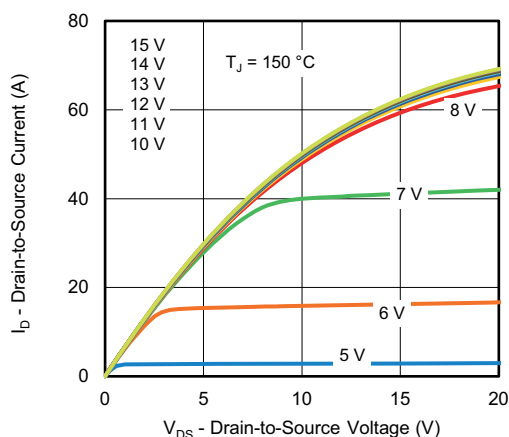
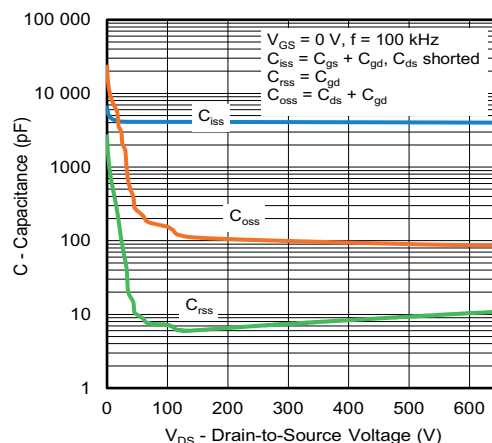
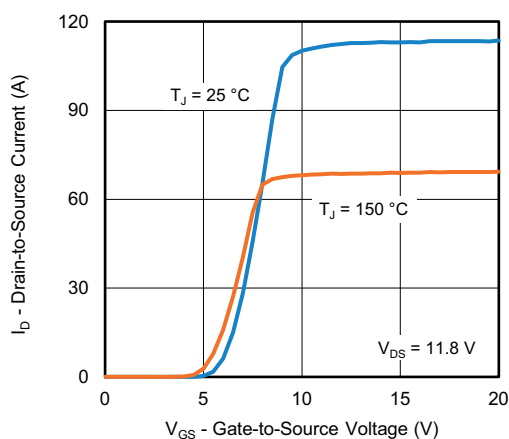
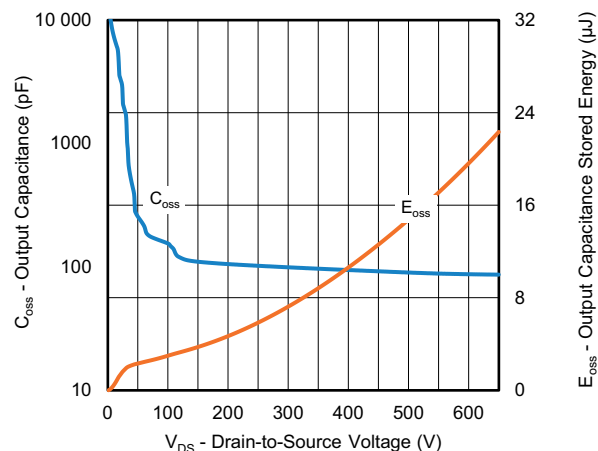
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	R_{thJA}	-	40	°C/W
Maximum junction-to-case (drain)	R_{thJC}	-	0.31	

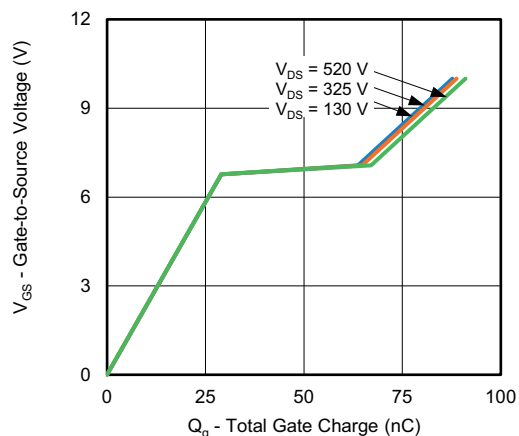
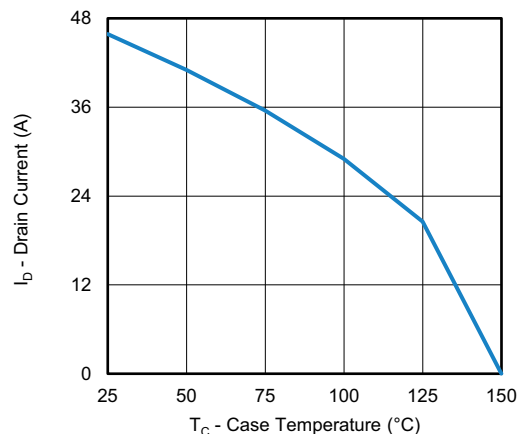
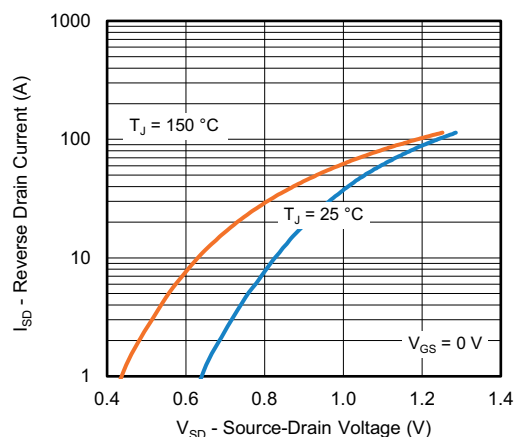
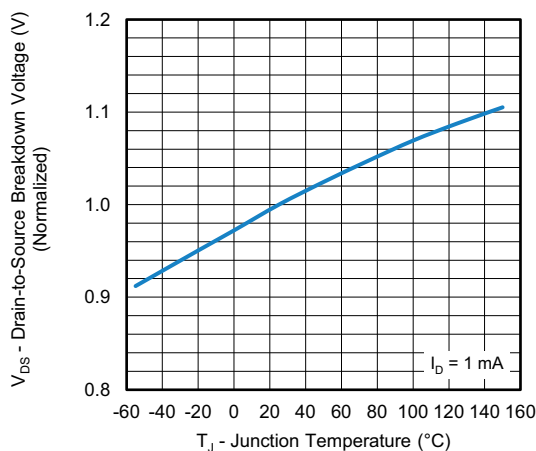
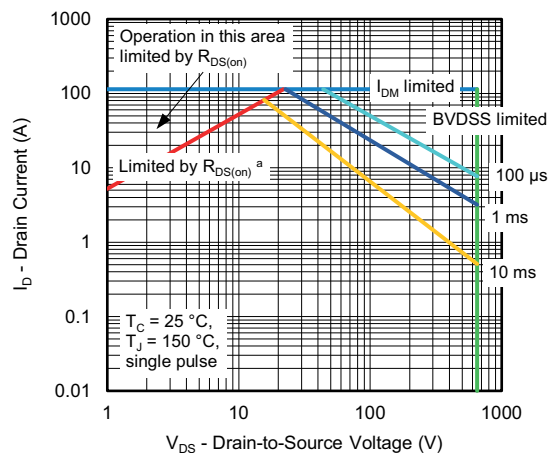
SPECIFICATIONS ($T_J = 25\text{ °C}$, unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-source breakdown voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA		650	-	-	V
V _{DS} temperature coefficient	ΔV _{DS} /T _J	Reference to 25 °C, I _D = 1 mA		-	0.63	-	V/°C
Gate-source threshold voltage (N)	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA		3.0	-	5.0	V
Gate-source leakage	I _{GSS}	V _{GS} = ± 20 V		-	-	± 100	nA
Zero gate voltage drain current	I _{DSS}	V _{DS} = 650 V, V _{GS} = 0 V		-	-	1	μA
		V _{DS} = 520 V, V _{GS} = 0 V, T _J = 125 °C		-	-	2	mA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 22 A	-	0.066	0.080	Ω
Forward transconductance ^a	g _{fs}	V _{DS} = 20 V, I _D = 22 A		-	20	-	S
Dynamic							
Input capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = 100 V, f = 100 KHz		-	4090	-	pF
Output capacitance	C _{oss}			-	153	-	
Reverse transfer capacitance	C _{rss}			-	7	-	
Effective output capacitance, energy related ^a	C _{o(er)}	V _{DS} = 0 V to 400 V, V _{GS} = 0 V		-	103	-	
Effective output capacitance, time related ^b	C _{o(tr)}			-	609	-	
Total gate charge	Q _g	V _{GS} = 10 V	I _D = 30 A, V _{DS} = 520 V	-	91	137	nC
Gate-source charge	Q _{gs}			-	29	-	
Gate-drain charge	Q _{gd}			-	38	-	
Turn-on delay time	t _{d(on)}	V _{DD} = 520 V, I _D = 22 A, V _{GS} = 10 V, R _g = 10.1 Ω		-	41	82	ns
Rise time	t _r			-	26	52	
Turn-off delay time	t _{d(off)}			-	107	161	
Fall time	t _f			-	14	28	
Gate input resistance	R _g	f = 1 MHz, open drain		0.7	1.5	3.0	Ω
Drain-Source Body Diode Characteristics							
Continuous source-drain diode current	I _S	MOSFET symbol showing the integral reverse p - n junction diode 		-	-	46	A
Pulsed diode forward current	I _{SM}			-	-	114	
Diode forward voltage	V _{SD}	T _J = 25 °C, I _S = 22 A, V _{GS} = 0 V		-	-	1.4	V
Reverse recovery time	t _{rr}	T _J = 25 °C, I _F = I _S = 22 A, di/dt = 100 A/μs, V _R = 400 V		-	214	428	ns
Reverse recovery charge	Q _{rr}			-	0.8	1.6	μC
Reverse recovery current	I _{RRM}			-	6.1	-	A

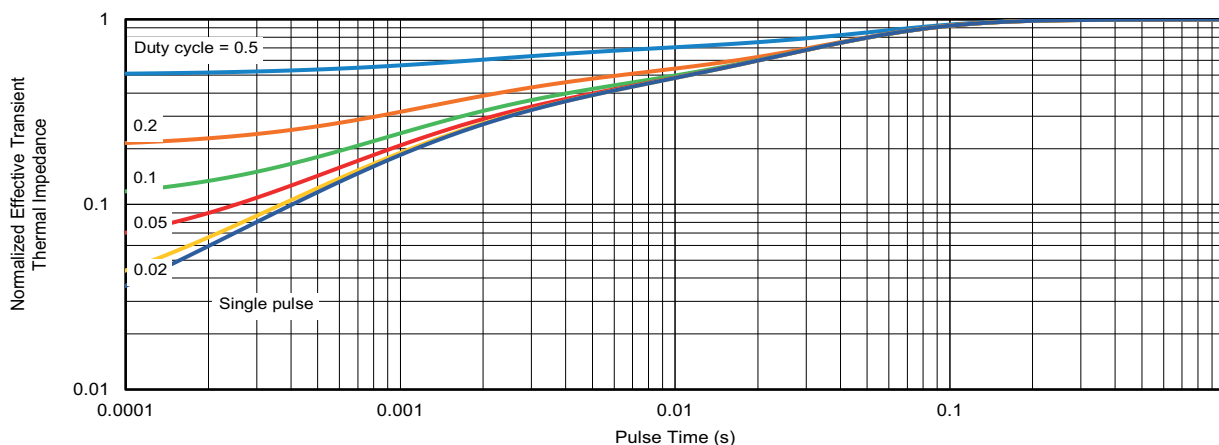
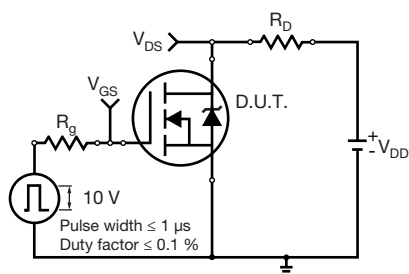
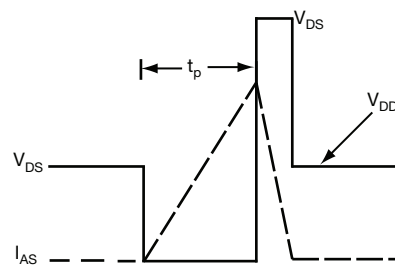
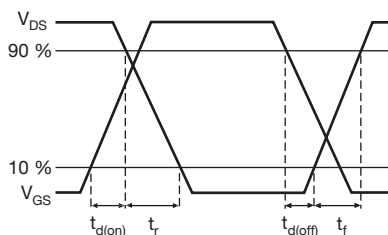
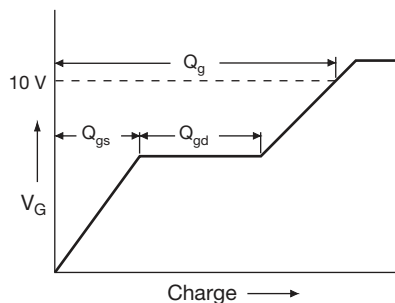
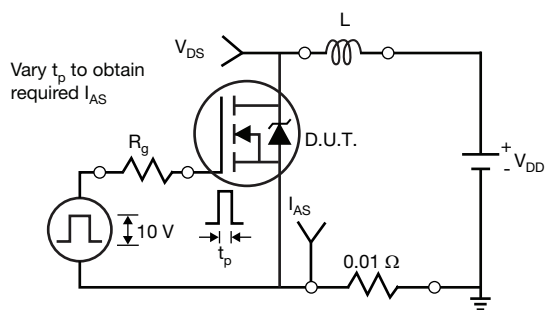
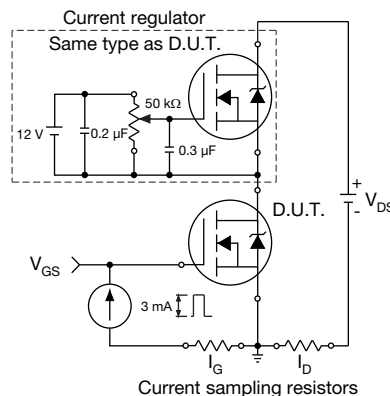
Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 V to 400 V
b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 V to 400 V

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

Fig. 1 - Typical Output Characteristics

Fig. 4 - Normalized On-Resistance vs. Temperature

Fig. 2 - Typical Output Characteristics

Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

Fig. 3 - Typical Transfer Characteristics

Fig. 6 - C_{oss} and E_{oss} vs. V_{DS}


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

Fig. 10 - Maximum Drain Current vs. Case Temperature

Fig. 8 - Typical Source-Drain Diode Forward Voltage

Fig. 11 - Temperature vs. Drain-to-Source Voltage

Fig. 9 - Maximum Safe Operating Area
Note

a. $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified


Fig. 12 - Normalized Transient Thermal Impedance, Junction-to-Case

Fig. 13 - Switching Time Test Circuit

Fig. 16 - Unclamped Inductive Waveforms

Fig. 14 - Switching Time Waveforms

Fig. 17 - Basic Gate Charge Waveform

Fig. 15 - Unclamped Inductive Test Circuit

Fig. 18 - Gate Charge Test Circuit

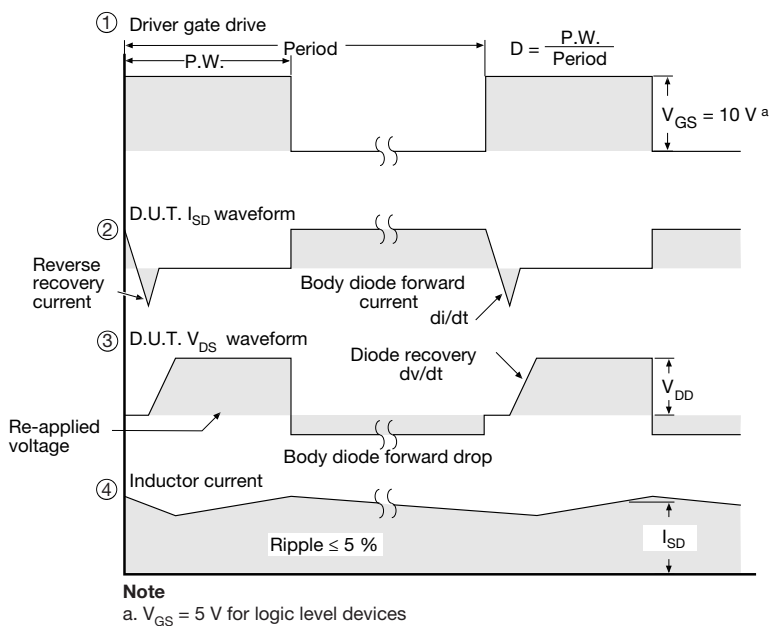
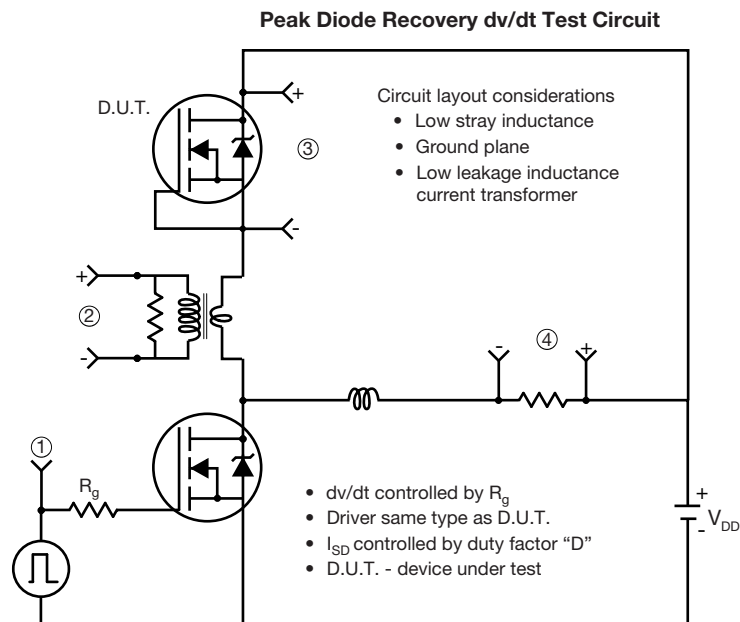


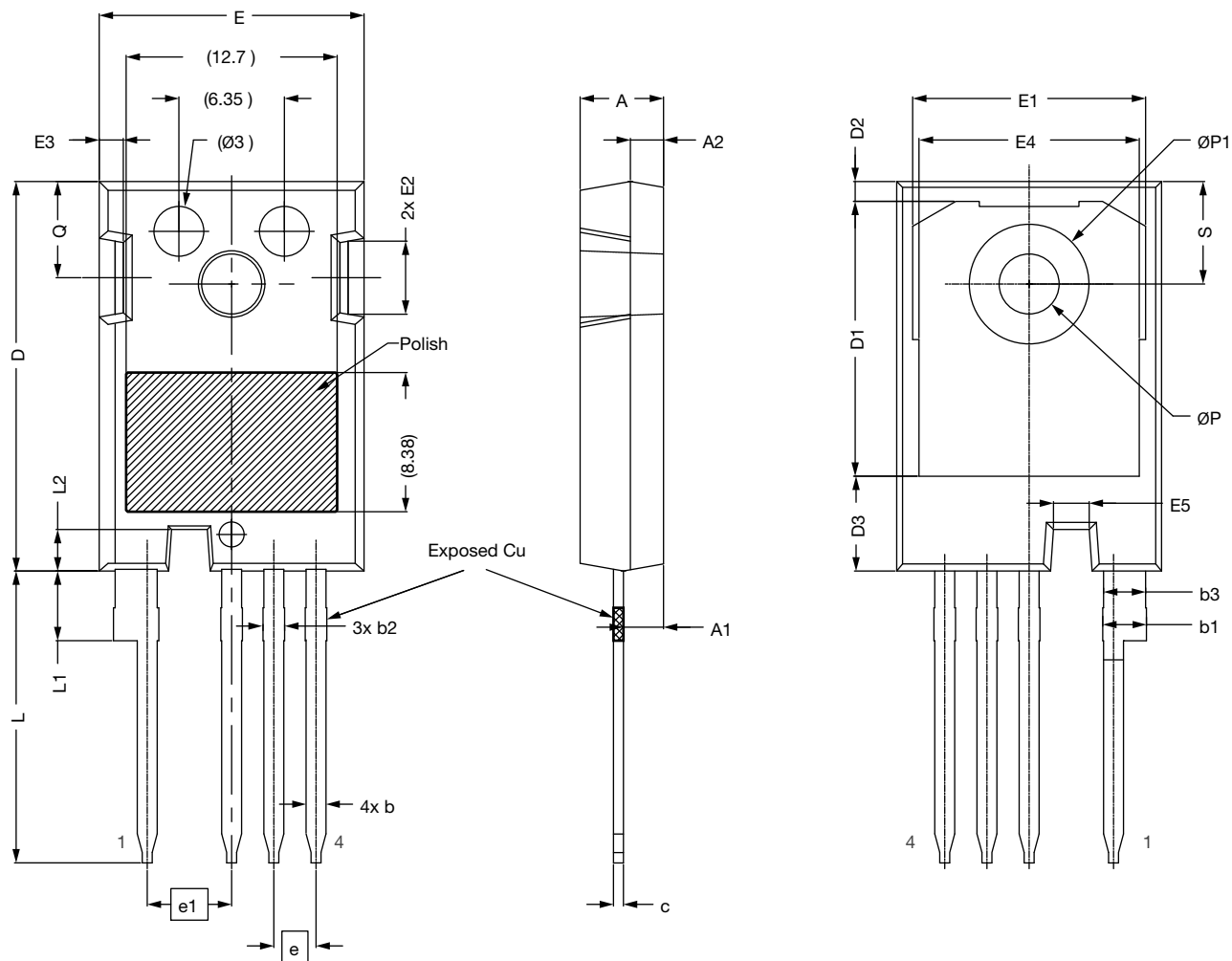
Fig. 19 - For N-Channel

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Case Outline for TO-247AD 4L Package

FACILITY CODE: 9





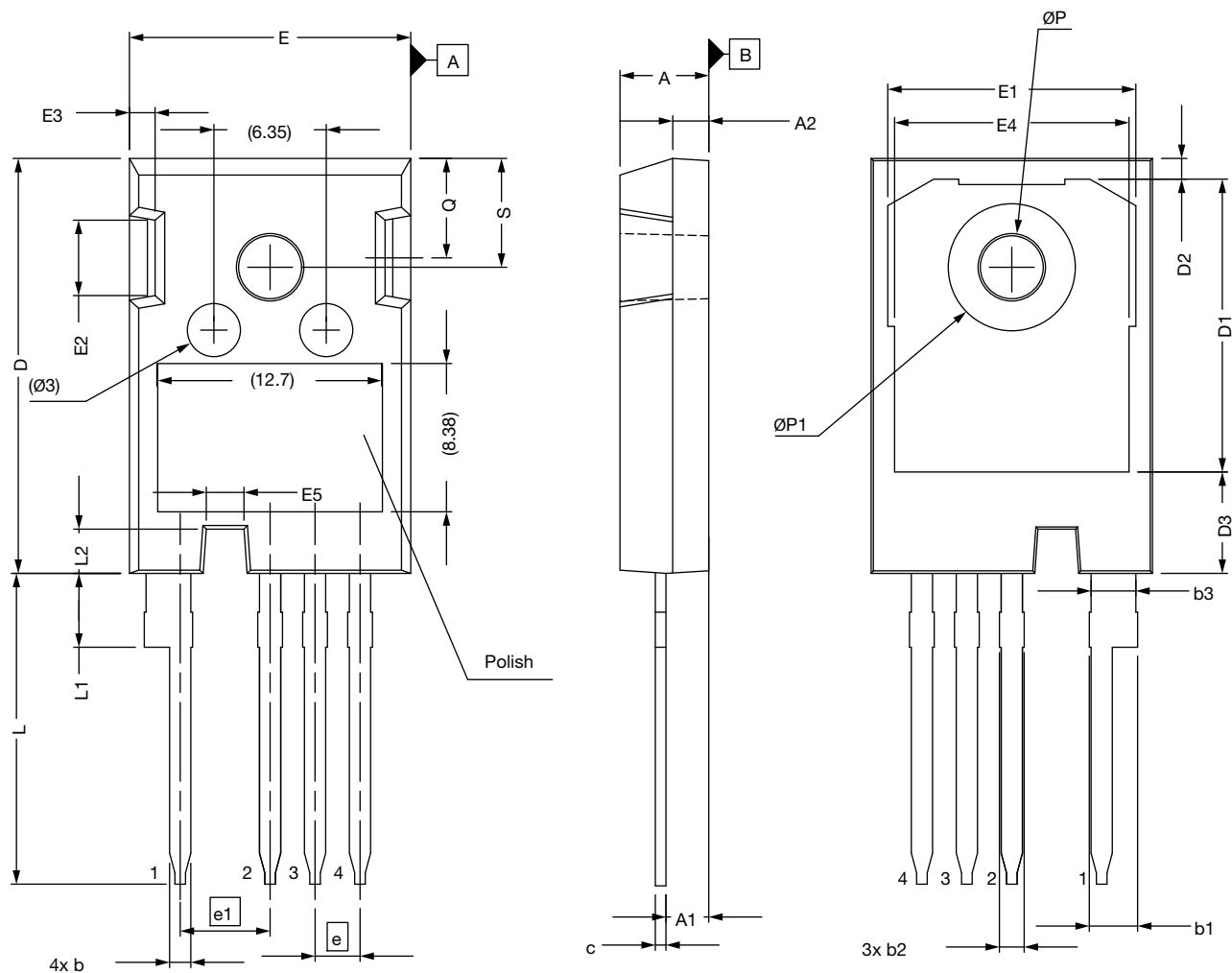
DIM.	MILLIMETERS	
	MIN.	MAX.
A	4.83	5.21
A1	2.29	2.54
A2	1.91	2.16
b	1.07	1.33
b1	2.39	2.94
b3	1.07	1.60
c	0.55	0.68
D	23.30	23.60
D1	16.25	17.65
D2	0.95	1.25
E	15.75	16.13
E1	13.10	14.15
E2	3.68	5.10
E3	1.00	1.90
E4	12.38	13.43
E5	1.95	2.35
e	2.54 BSC.	
e1	5.08 BSC.	
L	17.31	17.82
L1	3.97	4.37
L2	2.35	2.65
ØP	3.51	3.65
Q	5.49	6.00
S	6.04	6.30

Notes

- All dimensions are in mm. Angles are in degrees
- Dimension D and E do not include mold flash
- All metal surfaces: tin plated, except area of cut
- Dimensioning and tolerancing confirm to ASME Y14.5M-1994
- Creepage 1 is 8.58 mm (ref.) which is the distance alongside the surface between drain (pin 1) and trough the notch towards source (pin 2).
Creepage 2 is 7.95 mm (ref.) which is the distance from end of the copper slug on the backside of the package to either pin 2, pin 3 or pin 4



FACILITY CODE: N





DIM.	MILLIMETERS		
	MIN.	NOM.	MAX.
A	4.83	5.02	5.21
A1	2.29	2.41	2.54
A2	1.91	2.00	2.16
b	1.07	1.20	1.33
b1	2.39	2.67	2.94
b2	1.07	1.30	1.60
b3	2.39	2.53	2.69
c	0.55	0.60	0.68
D	23.30	23.45	23.60
D1	16.25	16.55	17.65
D2	0.95	1.19	1.25
D3	5.55	5.71	6.01
E	15.75	15.94	16.13
E1	13.10	14.02	14.15
E2	3.68	4.40	5.10
E3	1.00	1.45	1.90
E4	12.38	13.26	13.43
E5	1.95	2.15	2.35
e	2.54 BSC.		
e1	5.08 BSC.		
L	17.31	17.57	17.82
L1	3.97	4.19	4.37
L2	2.35	2.50	2.65
ØP	3.51	3.61	3.65
ØP1	7.19 ref.		
Q	5.49	5.79	6.00
S	6.04	6.17	6.30
ECN: S25-0851-Rev. C, 18-Jul-2025			
DWG: 6121			

Notes

- All dimensions are in mm
- Dimension D and E do not include mold flash.
- Creepage 1 is 8.40 mm (ref.) which is the distance alongside the surface between drain (pin 1) and trough the notch towards source (pin 2).
Creepage 2 is 7.70 mm (ref.) which is the distance from end of the copper slug on the backside of the package to either pin 2, pin 3 or pin 4



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